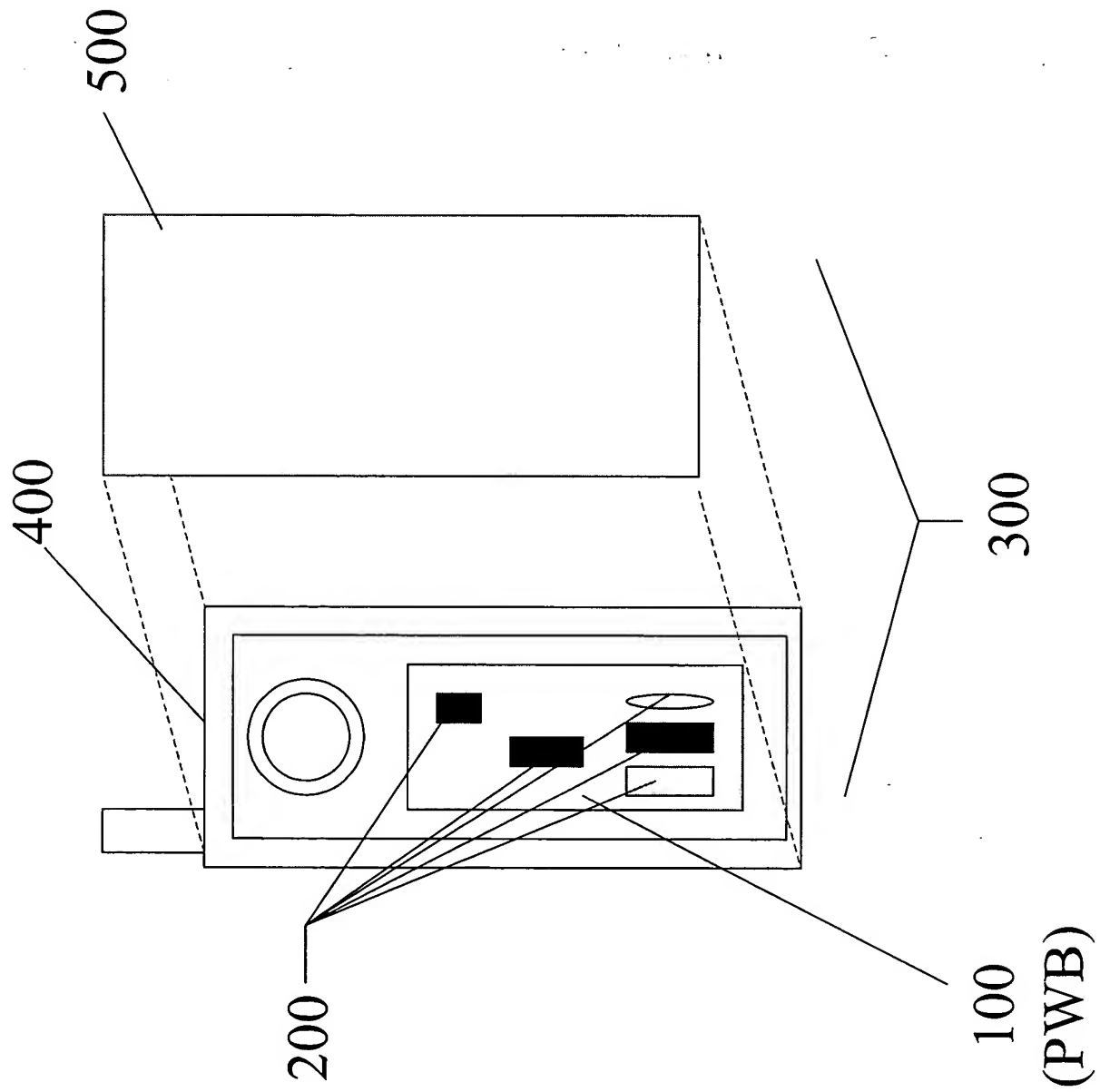


FIG. 1



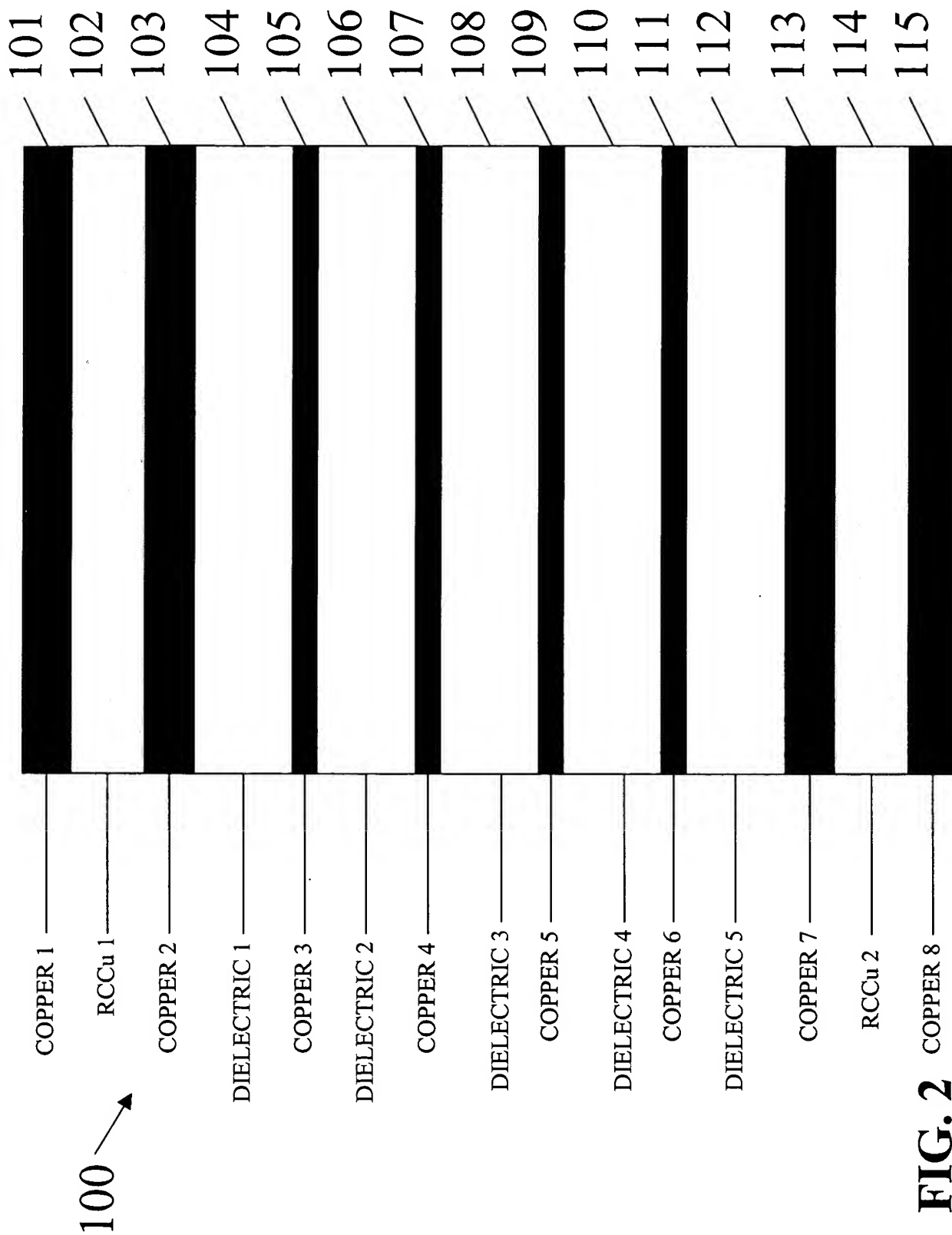


FIG. 3

LAYER	PWB LAYER THICKNESS/MATERIAL
COPPER 1	35 μm (+15/-10 μm)
RCCu 1	60 μm (+/-10 μm) RCCu (e.g. Matsushita R0880)
COPPER 2	35 μm (+15/-10 μm)
DIELECTRIC 1	75 μm (+/-25 μm) FR-4 (e.g. Matsushita 1766)
COPPER 3	17 μm (+2/-5 μm)
DIELECTRIC 2	75 μm (+/-25 μm) FR-4 (e.g. Matsushita 1766)
COPPER 4	17 μm (+2/-5 μm)
DIELECTRIC 3	75 μm (+/-25 μm) FR-4 (e.g. Matsushita 1766)
COPPER 5	17 μm (+2/-5 μm)
DIELECTRIC 4	75 μm (+/-25 μm) FR-4 (e.g. Matsushita 1766)
COPPER 6	17 μm (+2/-5 μm)
DIELECTRIC 5	75 μm (+/-25 μm) FR-4 (e.g. Matsushita 1766)
COPPER 7	35 μm (+15/-10 μm)
RCCu 2	60 μm (+/-10 μm) RCCu (e.g. Matsushita R0880)
COPPER 8	35 μm (+15/-10 μm)